

0.4A Avg.

600 Volts

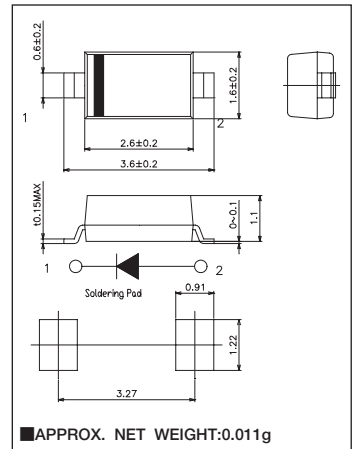
FRED

EP04RA60

■最大定格 Maximum Ratings (Ta=25°C : unless otherwise specified)

Item	Symbol	Conditions	Unit
くり返しピーク逆電圧 Repetitive Peak Reverse Voltage	V_{RRM}	600	V
平均整流電流 Average Rectified Forward Current	I_O	50Hz、正弦半波通電抵抗負荷 50Hz Half Sine Wave Resistive Load	$T_j=108^\circ\text{C}$ 0.4 A
			$T_a=31^\circ\text{C}^*1$ 0.3 A
実効順電流 R.M.S. Forward Current	$I_F(\text{RMS})$	0.628	A
サージ順電流 Surge Forward Current	I_{FSM}	8 50Hz正弦半波、1サイクル、非くり返し 50Hz Half Sine Wave, 1cycle, Non-repetitive	A
動作接合温度範囲 Operating Junction Temperature Range	T_{jw}	-40~+150	°C
保存温度範囲 Storage Temperature Range	T_{stg}	-40~+150	°C

■OUTLINE DRAWING(mm)



■電氣的・熱的特性 Electrical/Thermal Characteristics

Item	Symbol	Conditions	Min.	Typ.	Max.	Unit
ピーク逆電流 Peak Reverse Current	I_{RM}	$T_j=25^\circ\text{C}, V_{RM}=V_{RRM}$	—	—	10	μA
ピーク順電圧 Peak Forward Voltage	V_{FM}	$T_j=25^\circ\text{C}, I_{FM}=0.4\text{A}$	—	—	1.32	V
逆回復時間 Reverse Recovery Time	t_{rr}	$I_{FM}=0.4\text{A}, -di/dt=50\text{A}/\mu\text{s}, T_a=25^\circ\text{C}$	—	—	40	ns
熱抵抗 Thermal Resistance	$R_{th(j-l)}$	接合部・リード間 Junction to Lead	—	—	70	°C/W
	$R_{th(j-a)}$	接合部・周囲間 Junction to Ambient *1	—	—	300	°C/W

*1: プリント基盤実装 / Glass-Epoxy Substrate Mounted (Soldering Land=1×1mm, Both Sides)

■定格・特性曲線

